Tentative agenda of the 3D satellite workshop at the TIPP2011 conference

6/14/2011 2pm	Speaker Name	Presentation Title
2pm-2.25pm	Paul Franzon, NCSU, USA	Flavors of the 3D-IC technology and where it is applicable
2.25pm-2.50pm	Hans Gunther Moser, MPI, Germany	3D technology developments in Europe and European Union supported efforts
2.50pm-3.15pm	Masahiro Aoyagi, AIST, Japan	Japanese 3D status
3.15pm-3.30pm	Ray Yarema, FNAL, USA	TSV revolution and Fermilab's MPW experience
3.30pm-3.45pm	INFN, IN2P3, DoE	testimonial/application talks
3.45pm-4.25pm	Q&A + panel discussion + coffee	
4.25pm-4.50pm	Yasuo Arai, KEK, Japan	SOI technology for monolithic and 3D integrated detectors
4.50pm-5.15pm	Craig Keast, MIT-LL, USA	3D-IC enabler of advanced focal planes
5.15pm-5.40pm	Bob Patti, Tezzaron, USA	3D-IC for real chips and prospectives
5.40pm-5.55pm	Zvi Or-Bach, MonolithIC 3D	The Monolithic 3D-IC
5.55pm-6.20	Q&A + panel discussion + tea	
6.20pm-6.30pm	3D-IC workshop conclusions	